

# **2024 IEEE CPMT Symposium Japan (ICSJ 2024)**

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13-15 November 2024**



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	<i>Bo-Heng Chen, Wei-Hong Lai, Chin-Li Kao, Alexcc Wang and CP Hung</i> (Advanced Semiconductor Engineering (ASE) Inc.)	

## 1F Room II

### 14:00-16:20 Session 18: Power Electronics Materials and devices of UWBG and WBG semiconductors

*Kentaro Kaneko (Ritsumeikan University), Hiroki Imabayashi (University of Fukui)*

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	<i>Yohei Otoki</i> (Nagoya University <sup>1</sup> and National Yang Ming Chiao Tung University <sup>2</sup> )	
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	<i>Hideaki Tamimoto, Kazuki Matsumura, Kazuyuki Nakagawa, Kenji Ikura and Chikara Obama</i> (Renesas Electronics)	
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	<i>Nick Chenchao Zhong<sup>1</sup>, Haibo Fan<sup>1</sup> and Yuning Shi<sup>2</sup></i> (Nexperia Hong Kong <sup>1</sup> and Nexperia Shenzhen <sup>2</sup> )	
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	<i>Toya Yagura<sup>1</sup>, Yuri Shimizu<sup>1</sup>, Toyosuke Ibi<sup>1</sup>, Isao Takahashi<sup>1</sup> and Kentaro Kaneko<sup>2</sup></i> (Patentix Incorporated <sup>1</sup> and Ritsumeikan University <sup>2</sup> )	